

# Surface Mount Trench MOS Barrier Schottky Rectifiers

**TMBS® eSMP® Series**


Top view

Bottom view

**SMF (DO-219AB)**

Cathode Anode

**DESIGN SUPPORT TOOLS**
[click logo to get started](#)
**3D**  
Models  
Available

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3.0 A
$V_{RRM}$	100 V
$I_{FSM}$	55 A
$V_F$ at $I_F = 3$ A ( $T_A = 125$ °C)	0.62 V
$T_J$ max.	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

**FEATURES**

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**
**TYPICAL APPLICATIONS**

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

**MECHANICAL DATA**
**Case:** SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V3FM10	UNIT
Device marking code		3MB	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum average forward rectified current (fig.1)	$I_{F(AV)}^{(1)}$	2.5	A
	$I_{F(AV)}^{(2)}$	3.0	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	55	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	

**Notes**

(1) Free air, mounted on FR4 PCB, 2 oz. standard footprint

(2) Mounted on FR4 PCB, 2 oz. 10 mm x 10 mm copper pad areas

 (3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.59	-	V
	I <sub>F</sub> = 3.0 A			0.74	0.83	
	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 125 °C		0.52	-	
	I <sub>F</sub> = 3.0 A			0.62	0.70	
Reverse current	V <sub>R</sub> = 70 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.7	-	μA
		T <sub>A</sub> = 125 °C		500	-	
	V <sub>R</sub> = 100 V	T <sub>A</sub> = 25 °C		-	85	
		T <sub>A</sub> = 125 °C		900	3000	
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	240	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	V3FM10	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)(2)</sup>	125	°C/W
	R <sub>θJM</sub> <sup>(3)</sup>	22	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP<sub>D</sub>/dT<sub>J</sub> < 1/R<sub>θJA</sub>
- (2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance R<sub>θJA</sub> – junction-to-ambient
- (3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance R<sub>θJM</sub> – junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3FM10-M3/H	0.015	H	3000	7" diameter plastic tape and reel
V3FM10-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V3FM10HM3/H <sup>(1)</sup>	0.015	H	3000	7" diameter plastic tape and reel
V3FM10HM3/I <sup>(1)</sup>	0.015	I	10 000	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

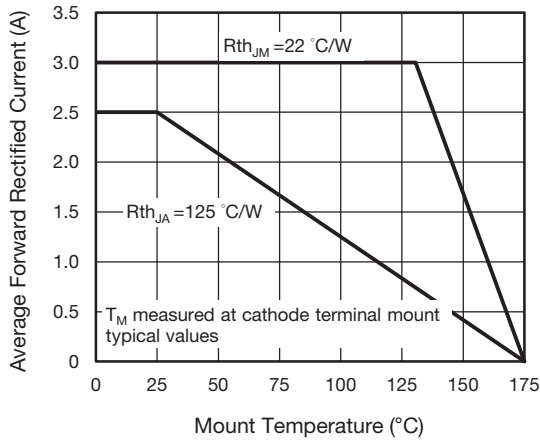


Fig. 1 - Maximum Forward Current Derating Curve

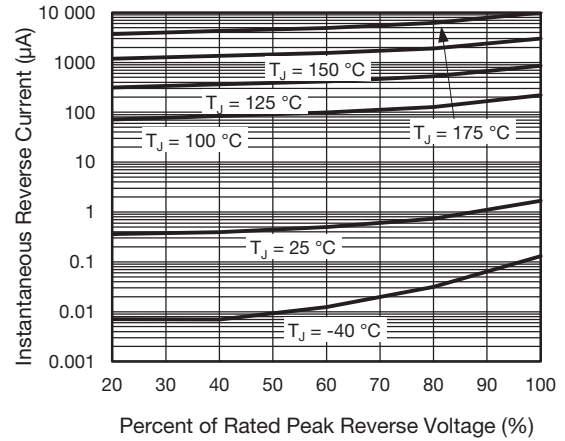


Fig. 4 - Typical Reverse Leakage Characteristics

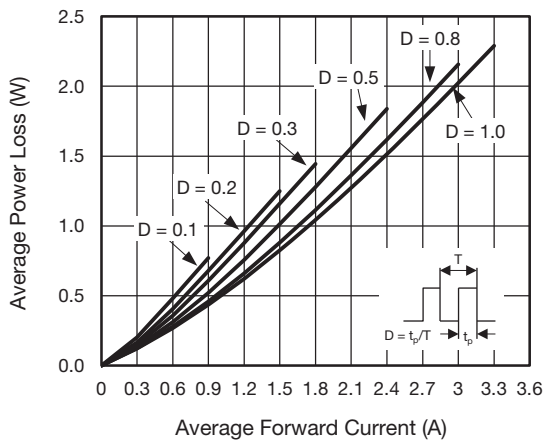


Fig. 2 - Average Power Loss Characteristics

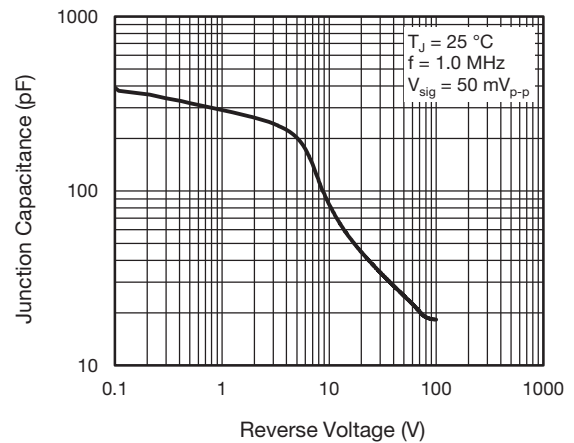


Fig. 5 - Typical Junction Capacitance

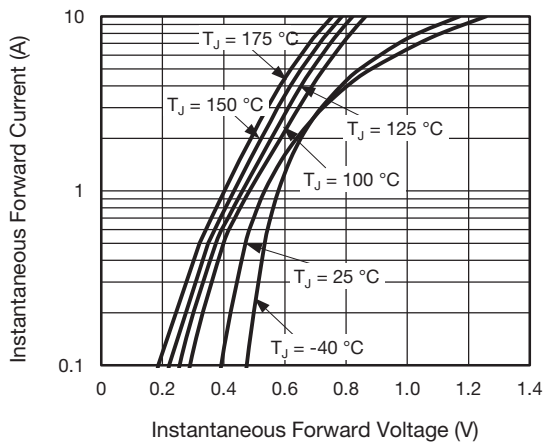


Fig. 3 - Typical Instantaneous Forward Characteristics

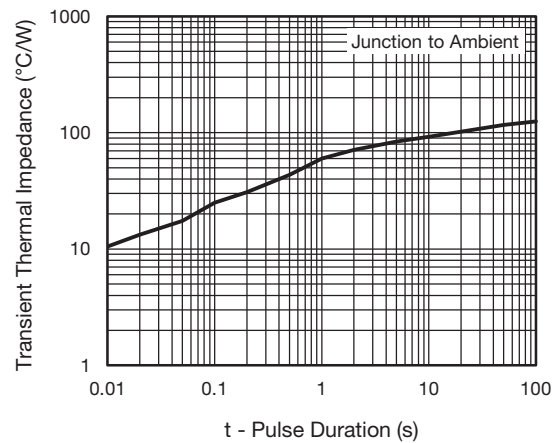
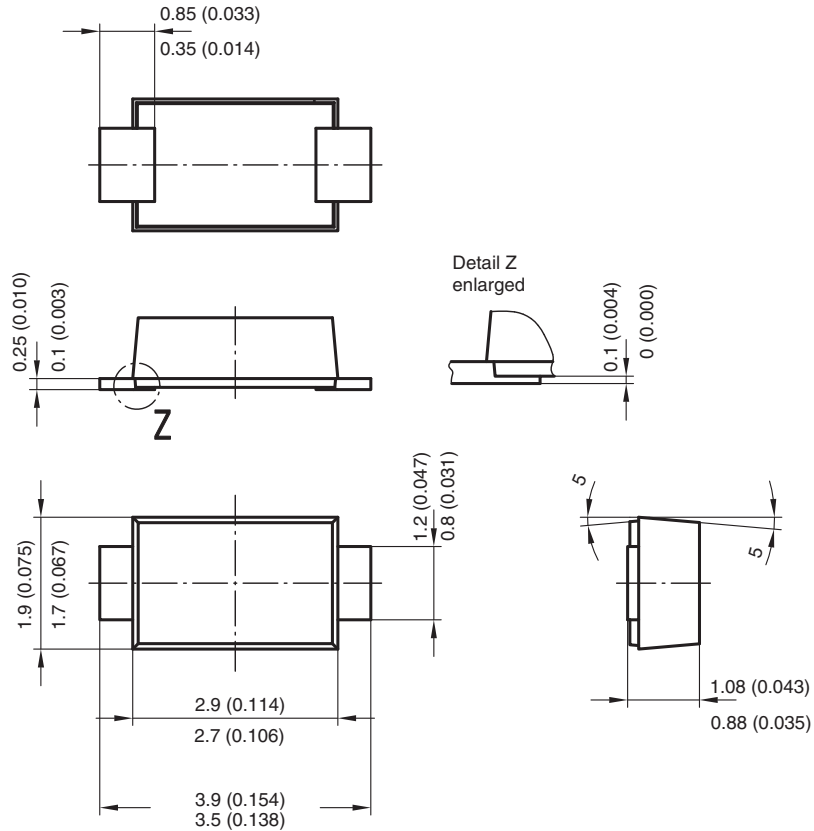


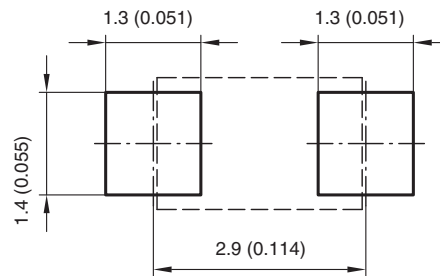
Fig. 6 - Typical Transient Thermal Impedance



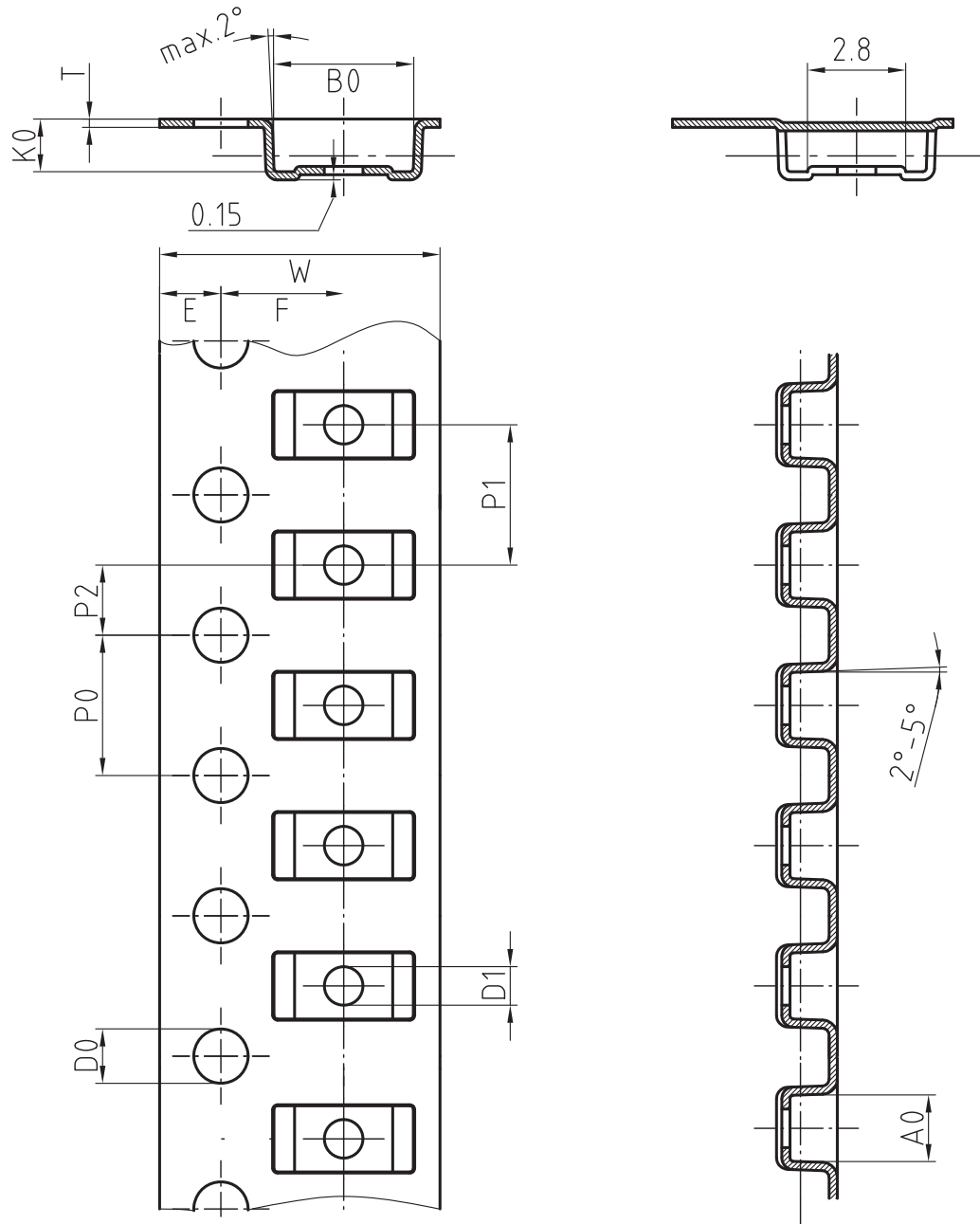
PACKAGE OUTLINE DIMENSIONS in millimeters (inches)



Foot print recommendation:



Created - Date: 15. February 2005  
 Rev. 3 - Date: 13. March 2007  
 Document no.: S8-V-3915.01-001 (4)  
 17247

**BLISTERTAPE DIMENSIONS** in millimeters: **SMF (DO-219AB)**


Mat:	A0	B0	K0	W	T	P0	P2	P1	D0	D1	E	F
PS	1.9	4.0	1.5	8.0	0.235	4.0	2.0	4.0	1.5	1	1.75	3.5

Document-No.: S8-V-3717.02-001 (3)

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